

IN THE CLAIMS

Please amend the claims as follows:

Claim 1. (Currently Amended) A method for producing a stress impedance effect element, the method comprising:

~~connecting opposite ends of a magnetostrictive amorphous thin wire and respective electrodes by ultrasonic bonding;~~

~~forming a groove in an elastic thin substrate having a thermal expansion coefficient equal to that of the magnetostrictive amorphous thin wire;~~

forming electrodes across the groove;

installing [[the]] a magnetostrictive amorphous thin wire in the groove, the magnetostrictive amorphous thin wire having a thermal expansion coefficient equal to that of the elastic thin substrate; [[and]]

connecting opposite ends of the magnetostrictive amorphous thin wire and the respective electrodes by ultrasonic bonding, the electrodes formed under the magnetostrictive amorphous thin wire; and

bonding together the magnetostrictive amorphous thin wire installed in the groove and the elastic thin substrate by applying an insulating adhesive across such that the insulating adhesive crosses over the magnetostrictive amorphous thin wire.

Claim 2. (Original) The method for producing a stress impedance effect element according to claim 1, wherein the magnetostrictive amorphous thin wire is a negative magnetostrictive amorphous thin wire.

Claim 3. (Original) The method for producing a stress impedance effect element according to claim 1, wherein the magnetostrictive amorphous thin wire has a diameter of not more than 20 micrometers.

Claim 4. (Cancelled)

Claim 5. (Currently Amended) A stress impedance effect element comprising:

(a) an elastic thin substrate ~~having a thermal expansion coefficient equal to that of a magnetostrictive amorphous thin wire, and~~ having a groove formed therein;

(b) electrodes [[each]] formed ~~at a respective one of the opposite ends of the magnetostrictive amorphous thin wire, by ultrasonic bonding across the groove; [[and]]~~

(c) a magnetostrictive amorphous thin wire provided in the groove and having a thermal expansion coefficient equal to that of the elastic thin substrate, opposite ends of the magnetostrictive amorphous thin wire connected to the respective electrodes by ultrasonic bonding, the electrodes formed under the magnetostrictive amorphous thin wire; and

~~[[(c)]]~~ (d) an insulating adhesive applied to the groove formed in the elastic thin substrate for bonding over the magnetostrictive amorphous thin wire [[to]] provided in the groove.

Claim 6. (Original) The stress impedance effect element according claim 5, wherein the magnetostrictive amorphous thin wire comprises a negative magnetostrictive amorphous thin wire.

Claim 7. (Original) The stress impedance effect element according claim 5, wherein the magnetostrictive amorphous thin wire has a diameter of not more than 20 micrometers.

Claim 8. (Cancelled)